

I) Please withdraw claims 1-14 as forth below:

(Withdrawn) 1. A method for preparing a photoresist layer for e-beam inspection comprising:

5 out-gassing said photoresist layer whereby an outgas from said photoresist layer during said e-beam inspection is substantially prevented.

(Withdrawn) 2. The method for of claim 1 wherein:

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said step of out-gassing said photoresist layer further comprising a step of implanting ions into said photoresist layer to activate an out-gassing from said photoresist layer.

15 (Withdrawn) 3. A method for preparing a photoresist layer for e-beam inspection comprising:

20 increasing a conductivity of said photoresist layer whereby electric charging of said photoresist layer during said e-beam inspection is substantially prevented.

(Withdrawn) 4. The method for of claim 3 wherein:

25 said step of increasing a conductivity of said photoresist layer further comprising a step of implanting conductive ions into said photoresist layer to increase a conductivity of said photoresist layer.

(Withdrawn) 5. The method for of claim 3 wherein:

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said step of increasing a conductivity of said photoresist layer further comprising a step of implanting carbon ions into said photoresist layer.

(Withdrawn) 6. The method for of claim 3 wherein:

5 said step of increasing a conductivity of said photoresist
layer further comprising a step of implanting indium ions
into said photoresist layer.

(Withdrawn) 7. The method for of claim 3 wherein:

10 said step of increasing a conductivity of said photoresist
layer further comprising a step of implanting Sb ions into
said photoresist layer.

(Withdrawn) 8. The method for of claim 3 wherein:

15 said step of increasing a conductivity of said photoresist
layer further comprising a step of implanting silicon ions
into said photoresist layer.

(Withdrawn) 9. The method for of claim 3 wherein:

20 said step of increasing a conductivity of said photoresist
layer further comprising a step of implanting metallic ions
into said photoresist layer.

25 (Withdrawn) 10. The method for of claim 3 wherein:

30 said step of increasing a conductivity of said photoresist
layer further comprising a step of implanting a conductive
ions at an implanting energy approximately 1000 ev into
said photoresist layer.

(Withdrawn) 11. The method for of claim 3 wherein:

5 said step of increasing a conductivity of said photoresist layer further comprising a step of implanting a conductive ions having an ion dosage in a approximate range 10^{16} /cm² to 10^{18} /cm² into said photoresist layer.

(Withdrawn) 12. The method for of claim 3 wherein:

10 said step of increasing a conductivity of said photoresist layer further comprising a step of plasma immersing ion implant a conductive ions into said photoresist layer.

(Withdrawn) 13. The method for of claim 3 further comprising:

15 out-gassing said photoresist layer whereby an outgas from said photoresist layer during said e-beam inspection is substantially prevented.

20 (Withdrawn) 14. The method for of claim 13 wherein:

25 said step of out-gassing said photoresist layer further comprising a step of implanting ions into said photoresist layer to activate an out-gassing from said photoresist layer.

(Original) 15. A photoresist layer for integrated circuit manufacture processed for e-beam inspection comprising:

30 an out-gas content less than 0.5 percents thus substantially prevent out-gassing from said photoresist layer during said e-beam inspection.

(Original) 16. A photoresist layer for integrated circuit manufacture processed for e-beam inspection comprising:

5 an electric resistivity less than 2000 ohm/cm² thus substantially prevent an electric charging of said photoresist layer during said e-beam inspection.

(Original) 17. A photoresist layer for integrated circuit manufacture comprising:

10 implanted conductive ions for increasing a conductivity of said photoresist layer.

(Original) 18. The photoresist layer for of claim 17 wherein:

15 said implanted conductive ions further comprising implanted carbon ions.

(Withdrawn) 19. The photoresist layer for of claim 17 wherein:

20 said implanted conductive ions further comprising implanted indium ions.

(Withdrawn) 20. The photoresist layer for of claim 17 wherein:

25 said implanted conductive ions further comprising implanted Sb ions.

(Withdrawn) 21. The photoresist layer for of claim 17 wherein:

30 said implanted conductive ions further comprising implanted silicon ions.

(Withdrawn) 22. The photoresist layer for of claim 17 wherein:

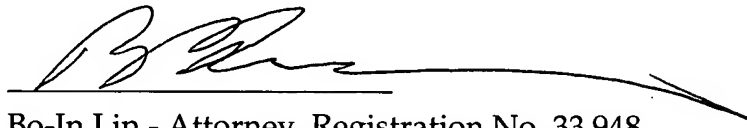
said implanted conductive ions further comprising
implanted metallic ions.

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Respectfully submitted
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By

A handwritten signature in black ink, appearing to read 'Bo-In Lin', is written over a horizontal line.

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